

ABSTRACT

A method for forming a solder resist pattern includes laminating a semi-cured thermosetting film on both sides of a substrate and laser ablating the laminated thermosetting film according to a solder resist mask pattern. The method is applicable to multilayer printed circuit boards, which are fabricated either by the buildup process or the parallel process. Lower manufacturing costs and improved accuracy of the solder resist pattern can be achieved due to the simplified process.

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